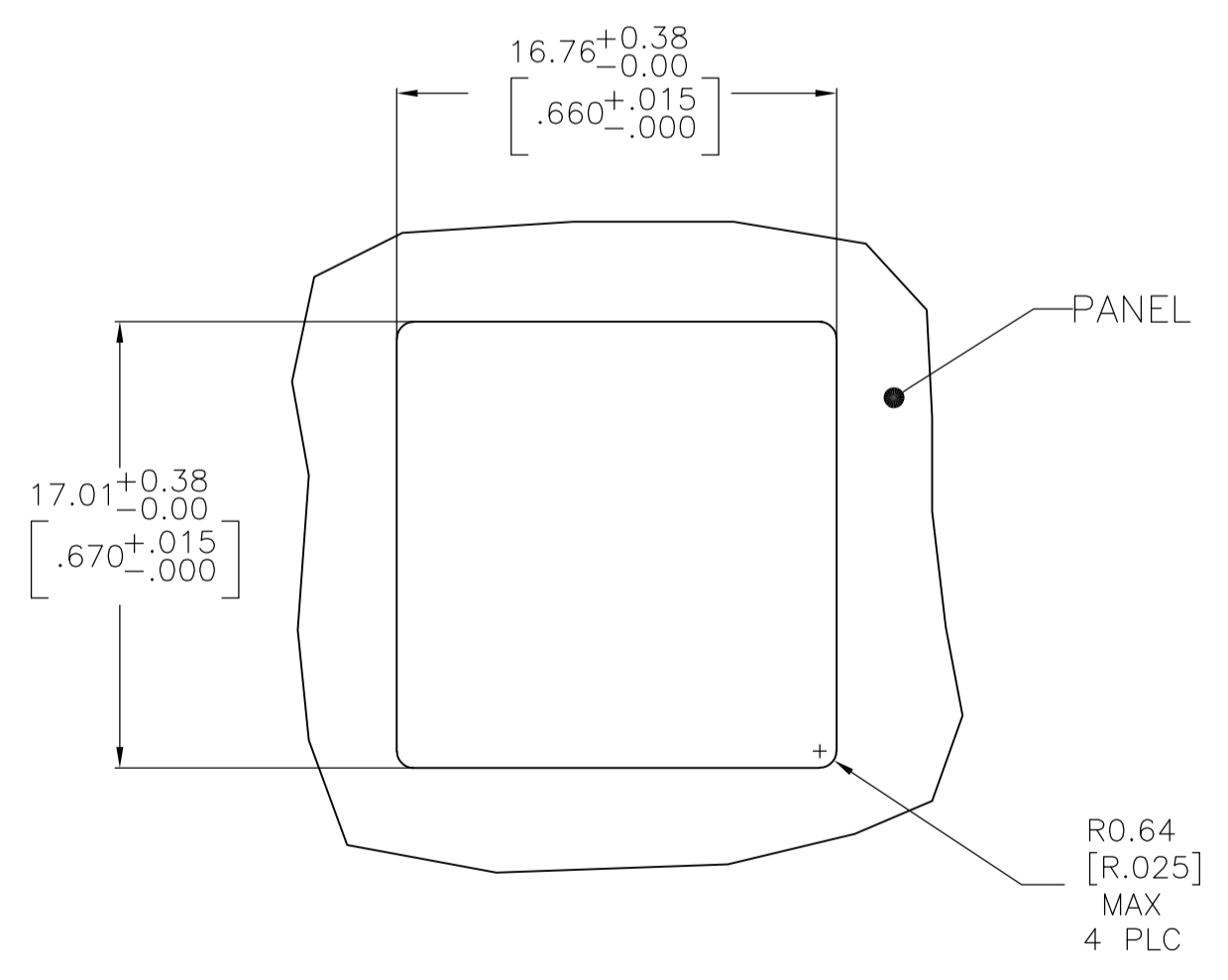


RECOMMENDED PRINTED
 CIRCUIT BOARD LAYOUT
 COMPONENT SIDE SHOWN



RECOMMENDED PANEL
 CUTOUT

- MATERIAL:
 HOUSING – POLYESTER MOLDING COMPOUND, COLOR: BLACK
 TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27μm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81μm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27μm[.000050] MIN THICK NICKEL UNDERPLATE
 SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0μm [.000120] MIN THICK REFLOWED TIN.

2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

2.79-3.30 [.120±.010]	5557969-2
2.79-3.56 [.125±.015]	5557969-1
DIM A	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN A FERNANDEZ-DOCKS 06JUN2005 CHK J. WESTMAN 06JUN2005		Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S. FLICKINGER 06JUN2005 NAME	
0 PLC ± -		1 PLC ± -		PRODUCT SPEC	
1 PLC ± -		2 PLC ± 0.13[.005]		108-1163	
2 PLC ± -		3 PLC ± -		APPLICATION SPEC	
3 PLC ± -		4 PLC ± -		114-2048	
4 PLC ± -		ANGLES ± -		SIZE CASE CODE DRAWING NO RESTRICTED TO	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		WEIGHT -	
				A1 00779 5557969	
				CUSTOMER DRAWING SCALE 4:1 SHEET 1 OF 1 REV D	